

What are we doing/want to do

@ IFCA

- April 2006 Partner of EU project EUDET (R&D on detector for ILC)
- July 2006 National Program approved.
- So far, concentrated on silicon tracking:
  - Laser based silicon alignment. (on progress)
  - FE electronics for uStrips (getting ready, concrete collaborations, recruiting people...)

# Activities....

- New EUDET contract started mid-September (few months delay)
  - Currently at CMS: Know-how from Silicon HW alignment.
- Preparation/purchasing of bench test at Santander:
  - Lasers, mechanics, electronics.
  - Optically treated modules not yet available (several options under consideration)
  - Ready by 1st Quarter next year.
- 1st Test Beam at DESY 6 GeV electrons (16 Oct – 3 Nov)

# SiLC Prototype Modules

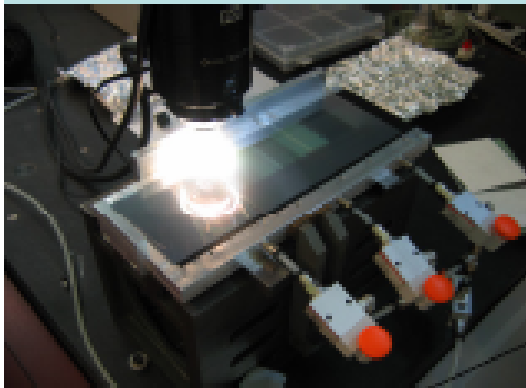
## 30 cm ladders

- 2 new ladders with 3 9-cm CMS sensors each, i.e. 28 cm strip length one equipped with VA1 chips (for a comparison) and the other with SiLC UMC 180 nm chip
  - This module was built in Paris

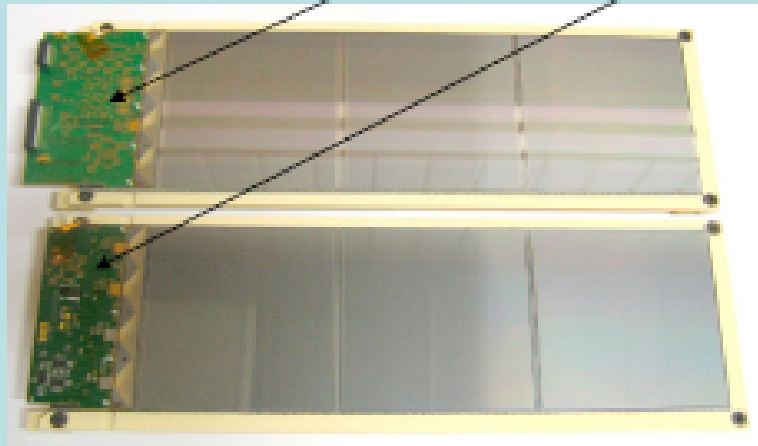
## Long ladder

- a new prototype with 10 GLAST sensors, i.e. 90 cm strip length equipped with VA1 and SiLC UMC 180 nm chip
- This module was built in in collaboration of Karlsruhe and Paris (with help from CERN)

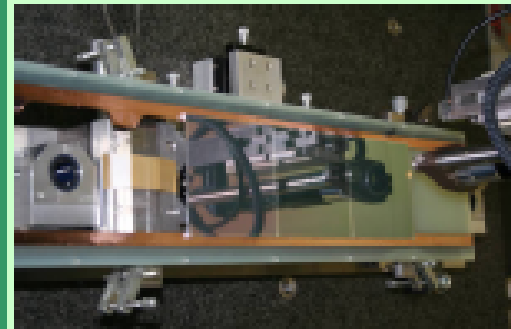
# Detector prototypes: CERN (A. Honma et al.), IEKP-Karlsruhe, LPNHE-Paris, IEHP-Vienna, Hamamatsu



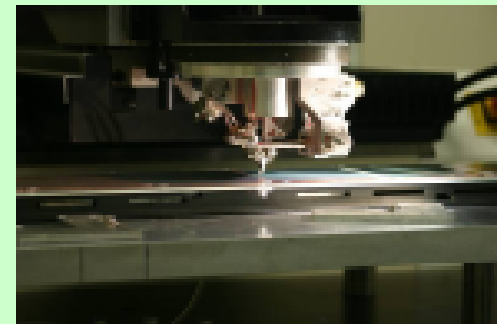
Assembly  
3 CMS sensors 28  
cm strip long  
Read out:  
VA1+180UMC r.o  
and all VA1 r.o.



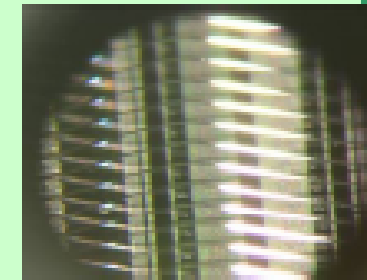
2 modules fabricated in Paris,  
bonding CERN on automated CMS system  
(Collab CERN-LPNHE)  
Ready by September 25th



Assembly:  
Module = 10  
GLAST sensors  
90 cm strip long

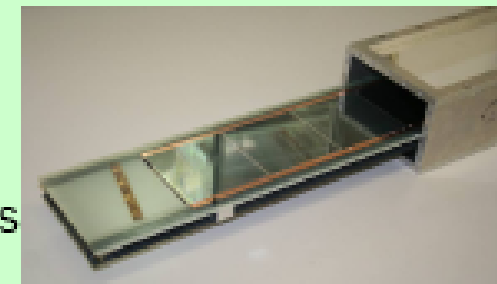


Bonding



The full construction done at IEKP

R.O.  
Pitch adapter +  
VA1 + 180UMC  
provided by Paris



Ready by September 25th